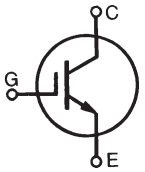
IXYS

Advance Technical Information

HiPerFAST™ IGBT
B2-Class High Speed IGBTs

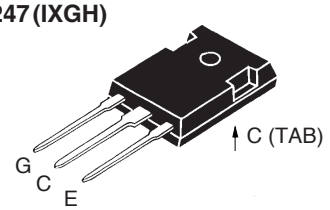
IXGH 32N90B2
IXGT 32N90B2

V_{CES} = 900 V
I_{C25} = 64 A
$V_{CE(sat)}$ = 2.7 V
$t_{fi\,typ}$ = 150 ns

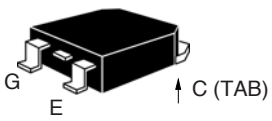


Symbol	Test Conditions	Maximum Ratings	
V_{CES}	T_J = 25°C to 150°C	900	V
V_{CGR}	T_J = 25°C to 150°C; R_{GE} = 1 MΩ	900	V
V_{GES}	Continuous	±20	V
V_{GEM}	Transient	±30	V
I_{C25}	T_C = 25°C (limited by leads)	64	A
I_{C110}	T_C = 110°C	32	A
I_{CM}	T_C = 25°C, 1 ms	200	A
SSOA (RBSOA)	V_{GE} = 15 V, T_{VJ} = 125°C, R_G = 10 Ω Clamped inductive load @ ≤ 600V	I_{CM} = 64	A
P_C	T_C = 25°C	300	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
Maximum lead temperature for soldering 1.6 mm (0.062 in.) from case for 10 s		300	°C
Plastic body for 10 s		260	°C
M_d	Mounting torque (TO-247)	1.13/10	Nm/lb.in.
Weight	TO-247	6	g
	TO-268	4	g

TO-247 (IXGH)



TO-268 (IXGT)



G = Gate, C = Collector,
E = Emitter, TAB = Collector

Symbol	Test Conditions		Characteristic Values (T_J = 25°C, unless otherwise specified) min.	typ.	max.	
$V_{GE(th)}$	I_C = 250 μA, V_{CE} = V_{GE}		3.0		5.0	V
I_{CES}	V_{CE} = V_{CES} V_{GE} = 0 V	T_J = 25°C T_J = 150°C			50 750	μA μA
I_{GES}	V_{CE} = 0 V, V_{GE} = ±20 V				±100	nA
$V_{CE(sat)}$	I_C = I_{C110}, V_{GE} = 15 V	 T_J = 125°C		2.2 2.1	2.7	V V

Features

- High frequency IGBT
- High current handling capability
- MOS Gate turn-on
  - drive simplicity

Applications

- PFC circuits
- Uninterruptible power supplies (UPS)
- Switched-mode and resonant-mode power supplies
- AC motor speed control
- DC servo and robot drives
- DC choppers

Advantages

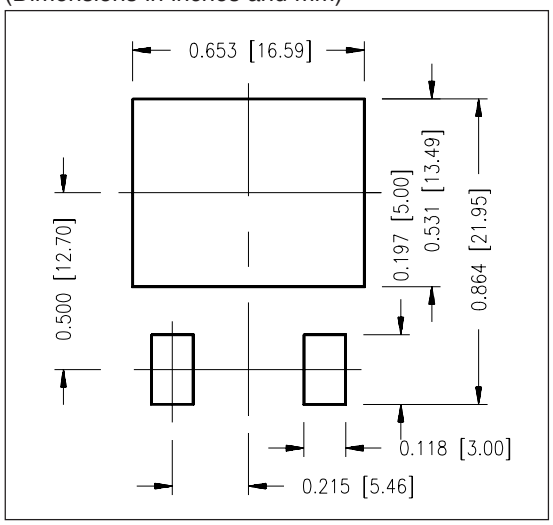
- High power density
- Very fast switching speeds for high frequency applications

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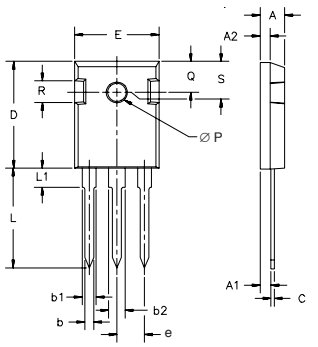
Symbol	Test Conditions	Characteristic Values (T_J = 25°C, unless otherwise specified) min.	typ.	max.	
g_{fs}	$I_C = I_{C110}$ A; V_{CE} = 10 V, Pulse test, t ≤ 300 μs, duty cycle ≤ 2 %	18	28		S
C_{ies}	V_{CE} = 25 V, V_{GE} = 0 V, f = 1 MHz		1790		pF
C_{oes}			121		pF
C_{res}			49		pF
Q_g	$I_C = I_{C110}$, V_{GE} = 15 V, V_{CE} = 0.5 V_{CES}		89		nC
Q_{ge}			15		nC
Q_{gc}			34		nC
$t_{d(on)}$	**Inductive load, T_J = 25°C**		20		ns
t_{ri}			22		ns
$t_{d(off)}$	$I_C = I_{C110}$, V_{GE} = 15 V		260	400	ns
t_{fi}	V_{CE} = 720 V, $R_G = R_{off}$ = 5 Ω		150		ns
E_{off}			2.6	4.5	mJ
$t_{d(on)}$	**Inductive load, T_J = 125°C**		20		ns
t_{ri}			22		ns
E_{on}	$I_C = I_{C110}$ A, V_{GE} = 15 V		0.5		mJ
	V_{CE} = 720 V, $R_G = R_{off}$ = 5 Ω	Note 1	3.8		mJ
$t_{d(off)}$			360		ns
t_{fi}			330		ns
E_{off}			5.75		mJ
R_{thJC}				0.42	K/W
R_{thCS}	(TO-247)		0.25		K/W

Note 1: E_{on} measured with a DSEP 30-12A ultrafast diode clamp.

Min. Recommended Footprint
(Dimensions in inches and mm)

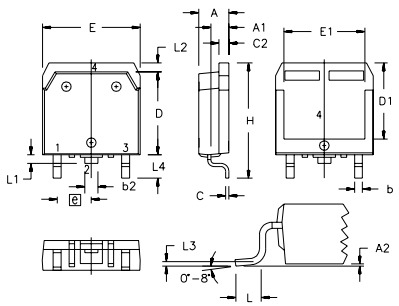


TO-247 AD Outline



Dim.	Millimeter Min.	Max.	Inches Min.	Max.
A	4.7	5.3	.185	.209
A_1	2.2	2.54	.087	.102
A_2	2.2	2.6	.059	.098
b	1.0	1.4	.040	.055
b_1	1.65	2.13	.065	.084
b_2	2.87	3.12	.113	.123
C	.4	.8	.016	.031
D	20.80	21.46	.819	.845
E	15.75	16.26	.610	.640
e	5.20	5.72	0.205	0.225
L	19.81	20.32	.780	.800
L1		4.50		.177
ØP	3.55	3.65	.140	.144
Q	5.89	6.40	0.232	0.252
R	4.32	5.49	.170	.216
S	6.15 BSC		242 BSC	

TO-268 Outline



SYM	INCHES MIN	MAX	MILLIMETERS MIN	MAX
A	.193	.201	4.90	5.10
A1	.106	.114	2.70	2.90
A2	.001	.010	0.02	0.25
b	.045	.057	1.15	1.45
b2	.075	.083	1.90	2.10
C	.016	.026	0.40	0.65
C2	.057	.063	1.45	1.60
D	.543	.551	13.80	14.00
D1	.488	.500	12.40	12.70
E	.624	.632	15.85	16.05
E1	.524	.535	13.30	13.60
e	.215 BSC		5.45 BSC	
H	.736	.752	18.70	19.10
L	.094	.106	2.40	2.70
L1	.047	.055	1.20	1.40
L2	.039	.045	1.00	1.15
L3	.010 BSC		0.25 BSC	
L4	.150	.161	3.80	4.10

IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,931,844 5,049,961 5,237,481 6,162,665 6,404,065 B1 6,683,344 6,727,585 4,850,072 5,017,508 5,063,307 5,381,025 6,259,123 B1 6,534,343 6,710,405 B2 6,759,692 4,881,106 5,034,796 5,187,117 5,486,715 6,306,728 B1 6,583,505 6,710,463 6771478 B2

Fig. 1. Output Characteristics @ 25 ºC

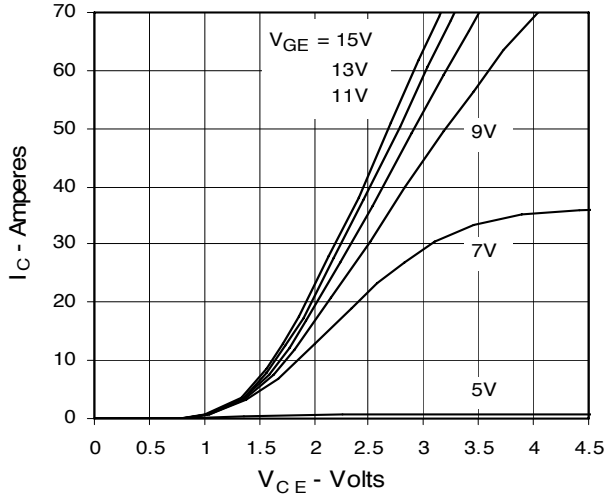


Fig. 2. Extended Output Characteristics @ 25 ºC

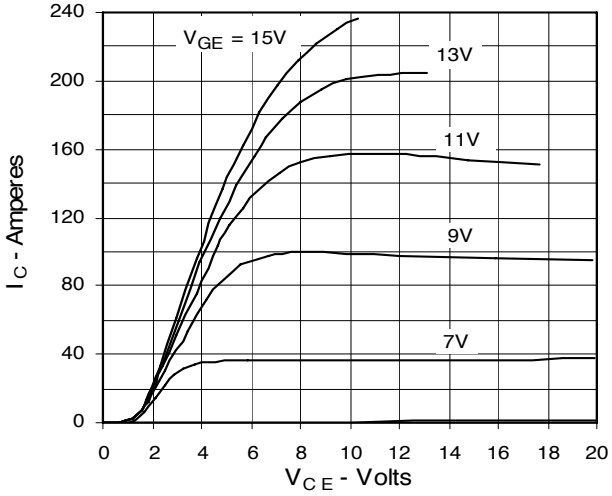


Fig. 3. Output Characteristics @ 125 ºC

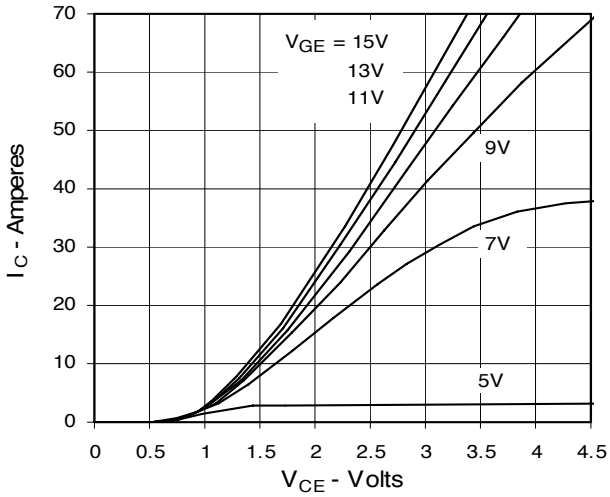


Fig. 4. Dependence of $V_{CE(sat)}$ on Temperature

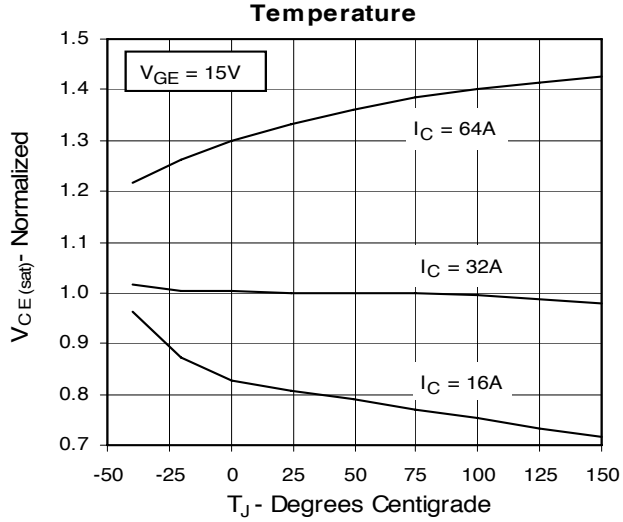


Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter voltage

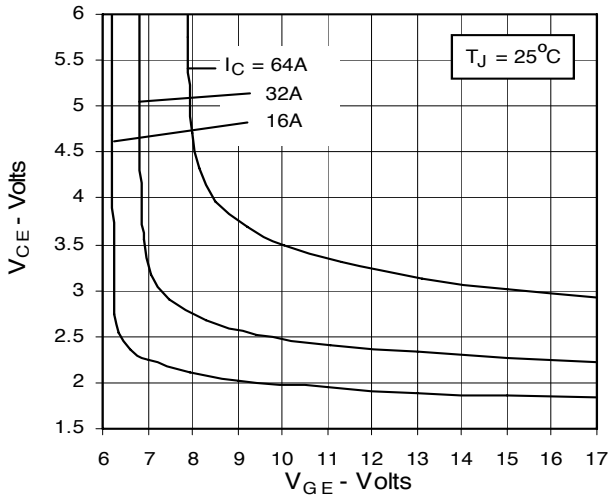
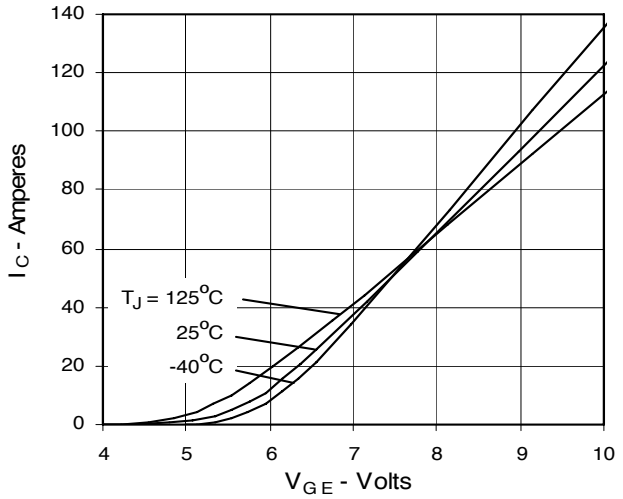


Fig. 6. Input Admittance



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Fig. 7. Transconductance

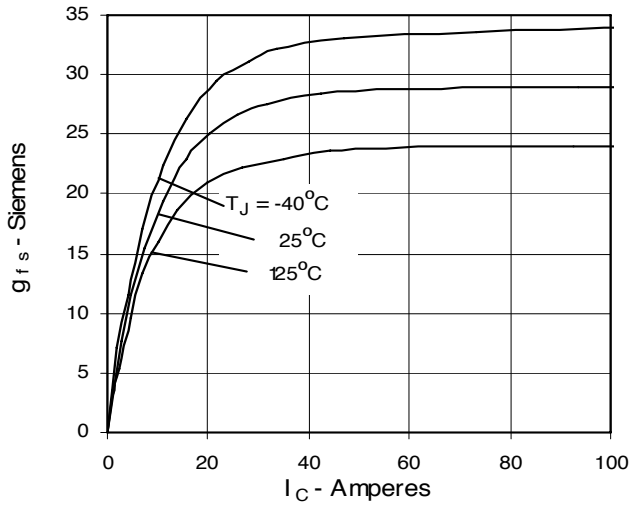


Fig. 8. Gate Charge

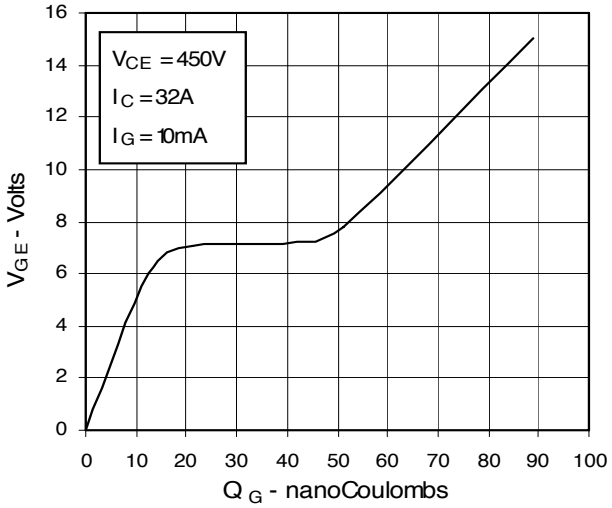


Fig. 9. Capacitance

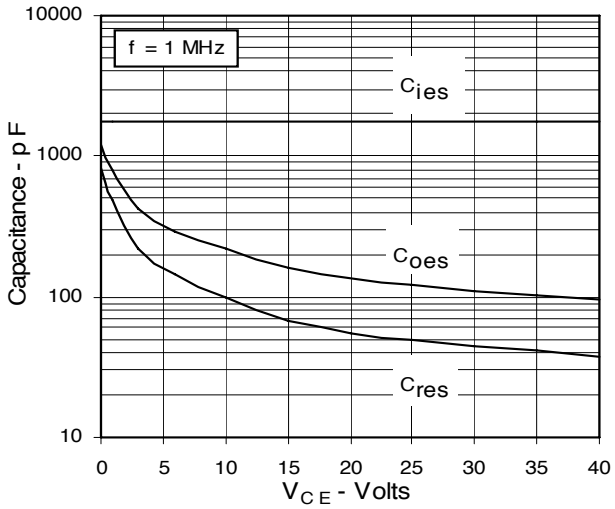


Fig. 10. Reverse-Bias Safe Operating Area

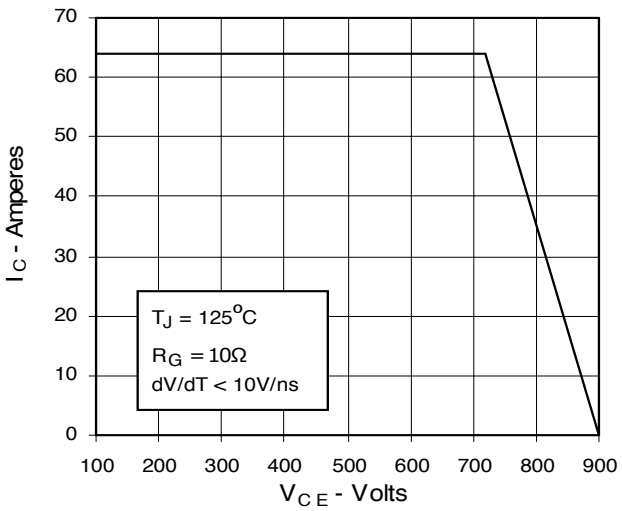
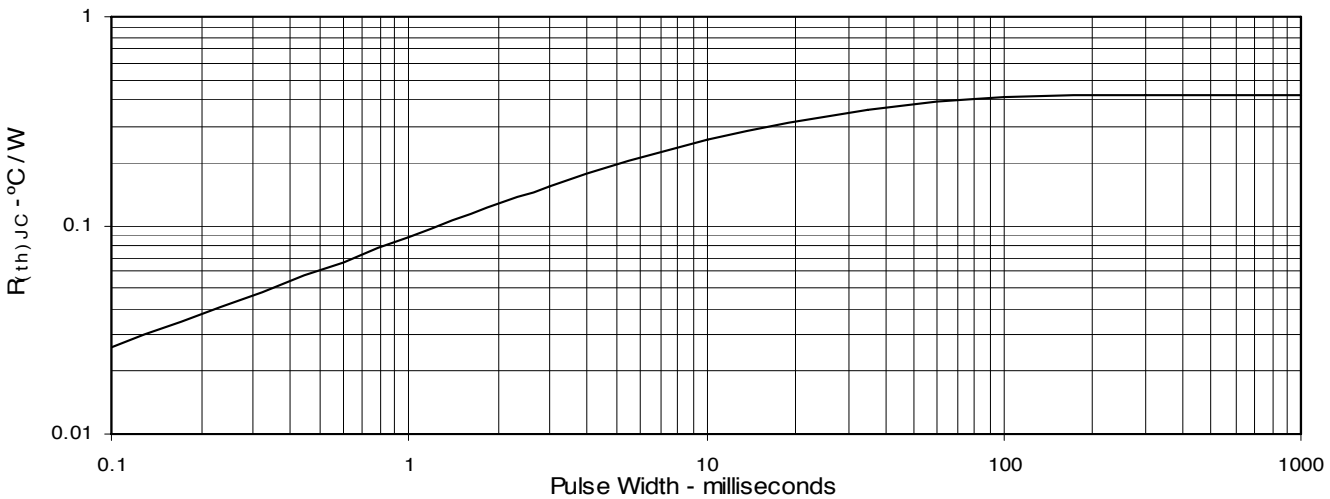


Fig. 11. Maximum Transient Thermal Resistance



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Fig. 12. Dependence of Turn-off Energy Loss on Gate Resistance

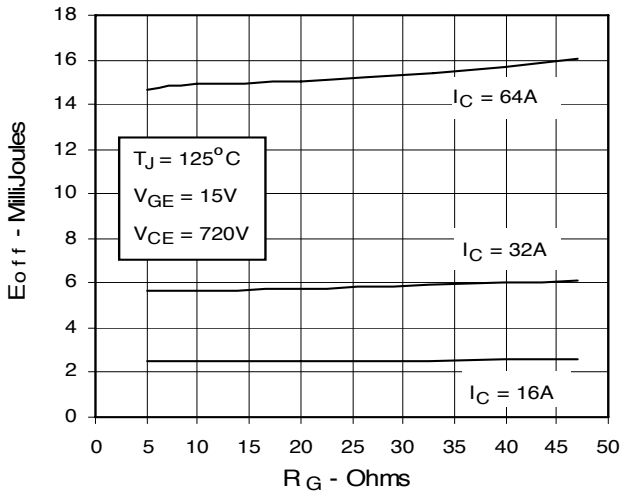


Fig. 13. Dependence of Turn-on Energy Loss on Gate Resistance

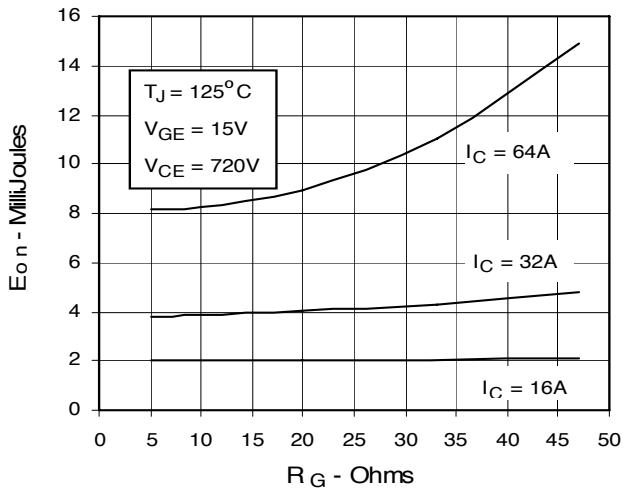


Fig. 14. Dependence of Turn-off Energy Loss on Collector Current

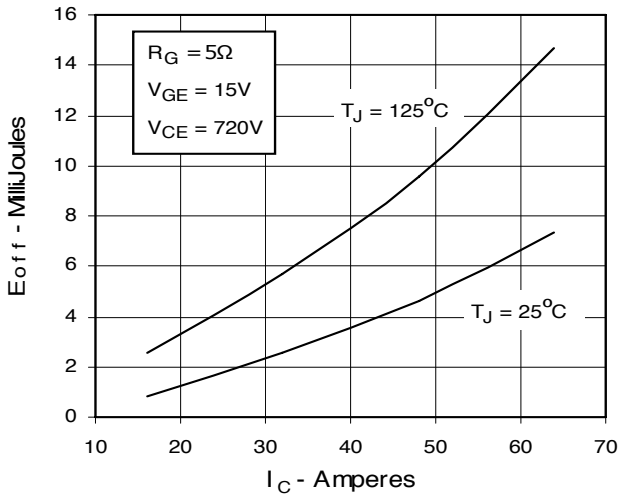


Fig. 15. Dependence of Turn-on Energy Loss on Collector Current

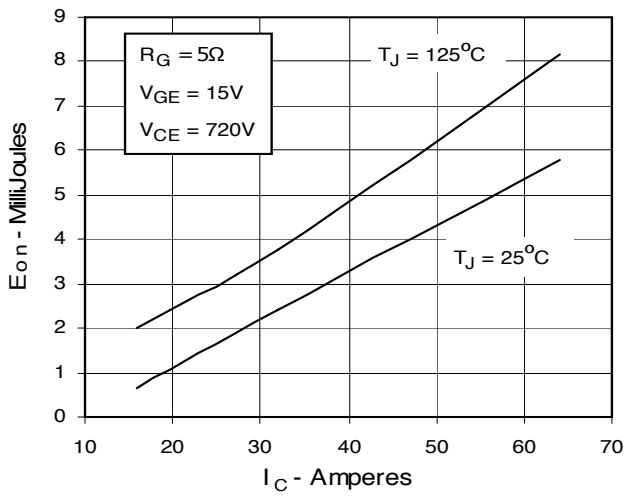


Fig. 16. Dependence of Turn-off Energy Loss on Temperature

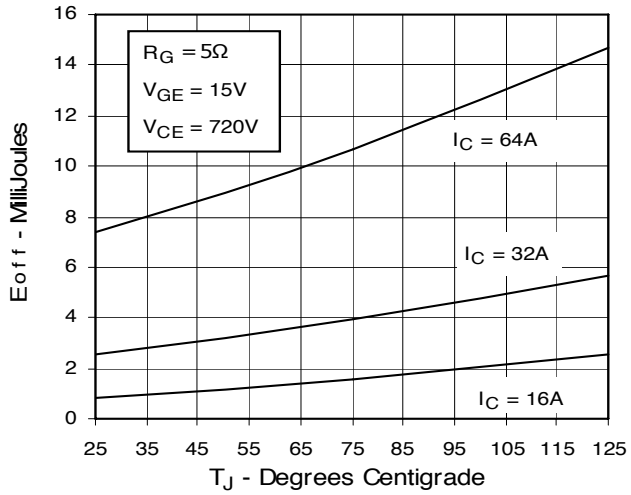
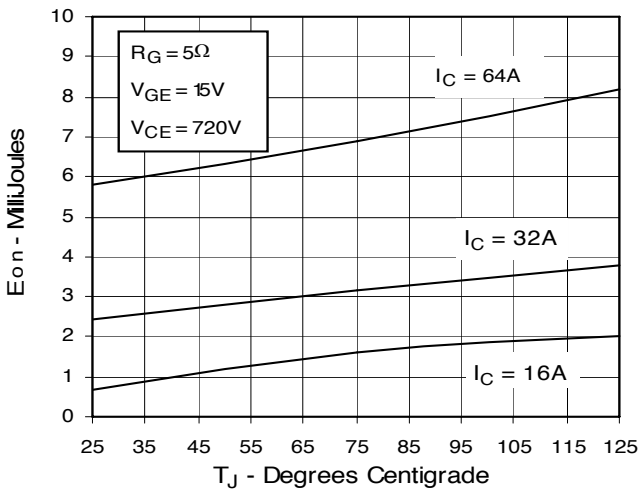


Fig. 17. Dependence of Turn-on Energy Loss on Temperature



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Fig. 18. Dependence of Turn-off Switching Time on Gate Resistance

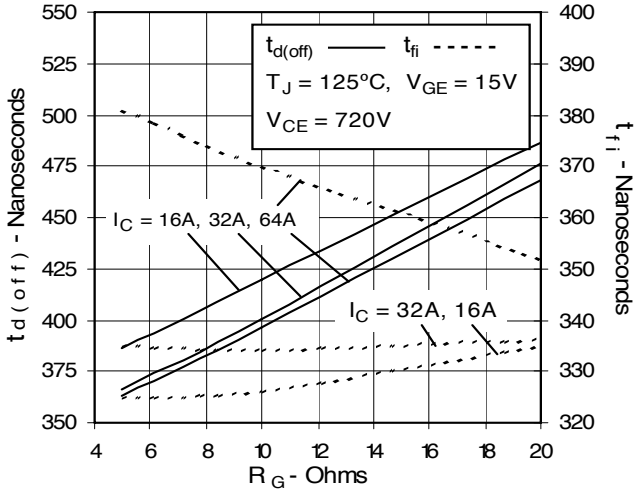


Fig. 19. Dependence of Turn-on Switching Time on Gate Resistance

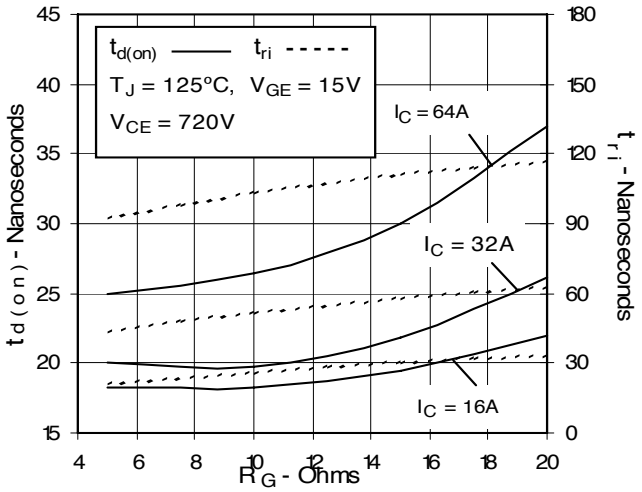


Fig. 20. Dependence of Turn-off Switching Time on Collector Current

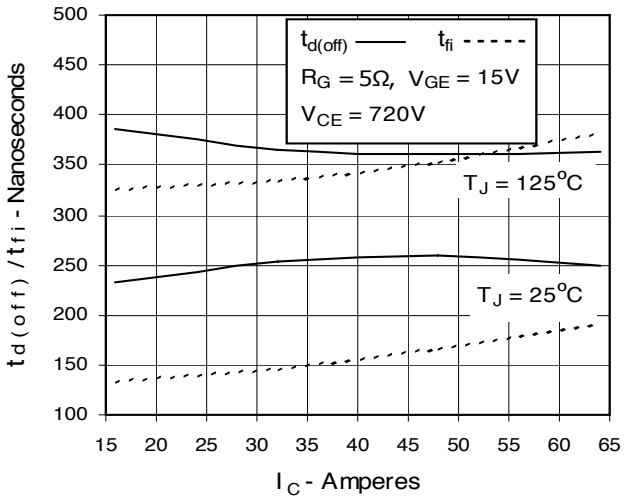


Fig. 21. Dependence of Turn-on Switching Time on Collector Current

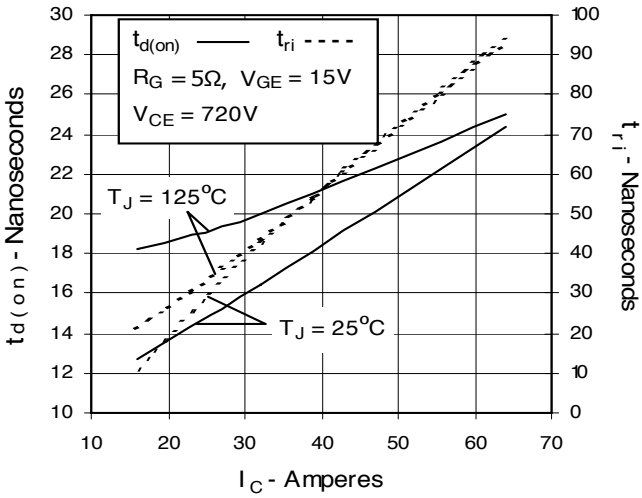


Fig. 22. Dependence of Turn-off Switching Time on Temperature

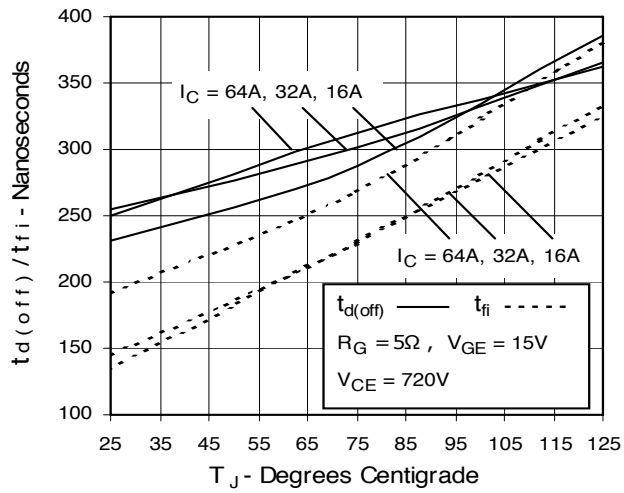
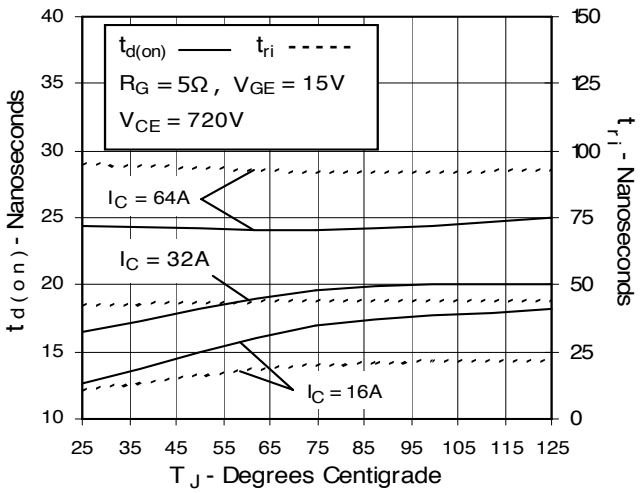


Fig. 23. Dependence of Turn-on Switching Time on Temperature



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ADVANCE TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from a subjective evaluation of the design, based upon prior knowledge and experience, and constitute a "considered reflection" of the anticipated objective result. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

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